

Notice of References Cited	Application/Control No. 09/841,582	Applicant(s)/Patent Under Reexamination NISHIYAMA ET AL.	
	Examiner David A. Zarneke	Art Unit 2891	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Quirk et al, Semiconductor Manufacturing Technology, Prentice Hall, 2001, p 545-546
	V	Tummala et al., Microelectronics Packaging Handbook-Semiconductor Packaging, Part II, 2nd Edition, Chapman & Hall, 1997, p 39, last full paragraph
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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